Renesas Electronics America Inc - R5F52318BDFM#30 Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

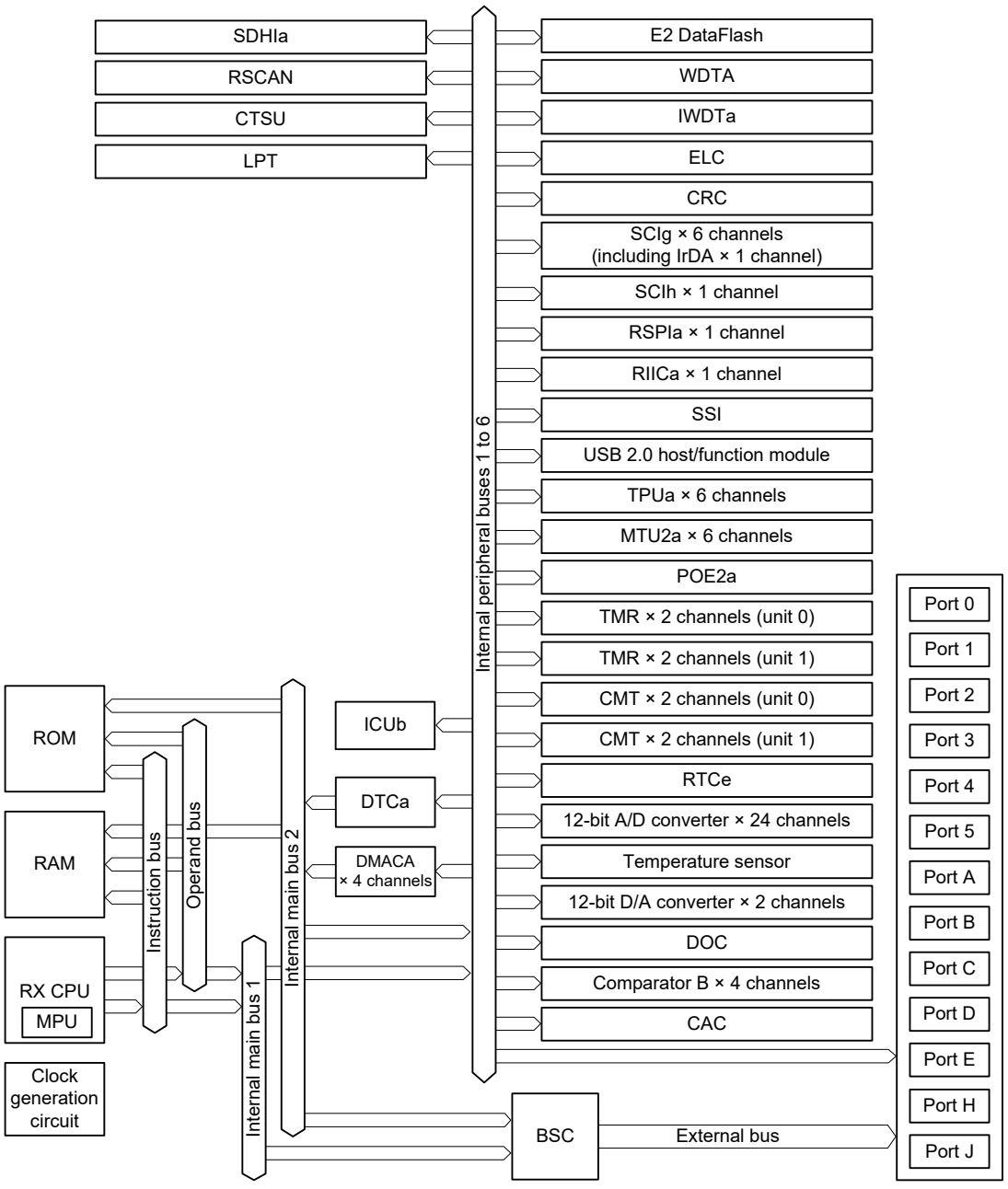
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	54MHz
Connectivity	CANbus, I²C, IrDA, SCI, SD/SDIO, SPI, SSI, USB OTG
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	43
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	8K x 8
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f52318bdfm-30

1.3 Block Diagram

Figure 1.2 shows a block diagram.



ICUb: Interrupt controller
DTCa: Data transfer controller
DMACA: DMA controller
BSC: Bus controller
WDTA: Watchdog timer
IWDTa: Independent watchdog timer
ELC: Event link controller
CRC: CRC (cyclic redundancy check) calculator
SCIg/SCIh: Serial communications interface
RSPIa: Serial peripheral interface
SSI: Serial sound interface
RIICa: I^2C bus interface
TPUa: 16-bit timer pulse unit
MTU2a: Multi-function timer pulse unit 2
POE2a: Port output enable 2
CMT: Compare match timer
RTCe: Realtime clock
DOC: Data operation circuit
CAC: Clock frequency accuracy measurement circuit
CTSU: Capacitive touch sensing unit
SDHIa: SD host interface
MPU: Memory protection unit
TMR: 8-bit timer
RSCAN: CAN module
LPT: Low power timer

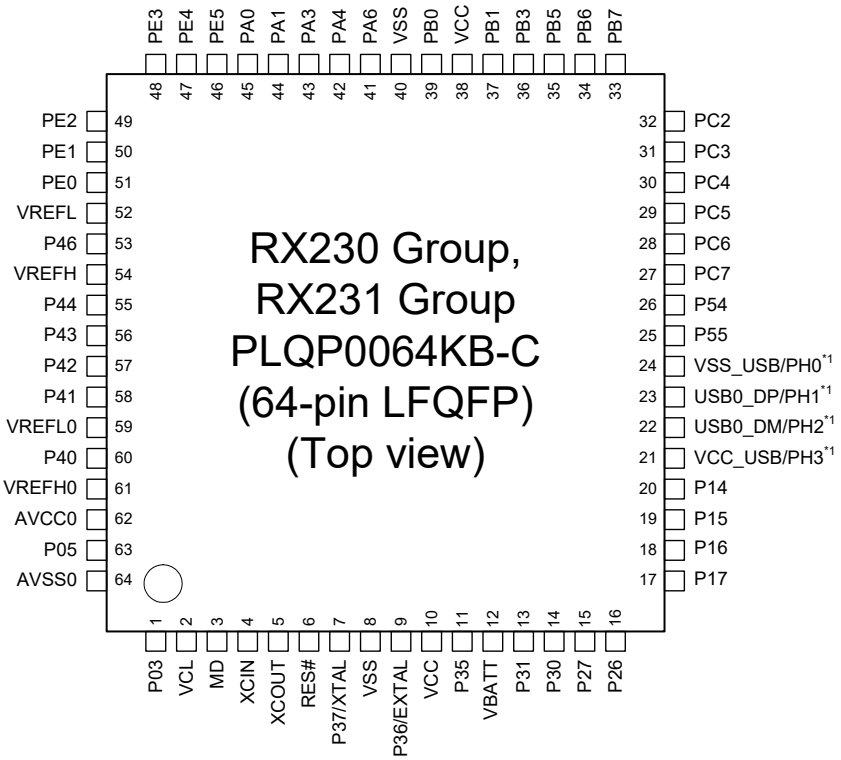
Figure 1.2 Block Diagram

1.4 Pin Functions

Table 1.5 lists the pin functions.

Table 1.5 Pin Functions (1/4)

Classifications	Pin Name	I/O	Description
Power supply	VCC	Input	Power supply pin. Connect it to the system power supply.
	VCL	—	Connect this pin to the VSS pin via a 4.7 μF smoothing capacitor used to stabilize the internal power supply. Place the capacitor close to the pin.
	VSS	Input	Ground pin. Connect it to the system power supply (0 V).
	VBATT	Input	Backup power pin
Clock	XTAL	Output	Pins for connecting a crystal. An external clock can be input through the EXTAL pin.
	EXTAL	Input	
	BCLK	Output	Outputs the external bus clock for external devices.
	XCIN	Input	Input/output pins for the sub-clock oscillator. Connect a crystal between XCIN and XCOUT.
	XCOUT	Output	
	CLKOUT	Output	Clock output pin.
Operating mode control	MD	Input	Pin for setting the operating mode. The signal levels on this pin must not be changed during operation.
	UB	Input	Pin used for boot mode (USB interface).
	UPSEL	Input	Pin used for boot mode (USB interface).
System control	RES#	Input	Reset pin. This MCU enters the reset state when this signal goes low.
CAC	CACREF	Input	Input pin for the clock frequency accuracy measurement circuit.
On-chip emulator	FINED	I/O	FINE interface pin.
Address bus	A0 to A23	Output	Output pins for the address.
Data bus	D0 to D15	I/O	Input and output pins for the bidirectional data bus.
Multiplexed bus	A0/D0 to A15/D15	I/O	Address/data multiplexed bus
Bus control	RD#	Output	Strobe signal which indicates that reading from the external bus interface space is in progress.
	WR#	Output	Strobe signal which indicates that writing to the external bus interface space is in progress, in single-write strobe mode.
	WR0#, WR1#	Output	Strobe signals which indicate that either group of data bus pins (D7 to D0, and D15 to D8) is valid in writing to the external bus interface space, in byte strobe mode.
	BC0#, BC1#	Output	Strobe signals which indicate that either group of data bus pins (D7 to D0 and D15 to D8) is valid in access to the external bus interface space, in single-write strobe mode.
	CS0# to CS3#	Output	Select signals for areas 0 to 3.
	WAIT#	Input	Input pin for wait request signals in access to the external space.
	ALE	Output	Address latch signal when address/data multiplexed bus is selected.
LVD	CMPA2	Input	Detection target voltage pin for voltage detection 2.
Interrupts	NMI	Input	Non-maskable interrupt request pin.
	IRQ0 to IRQ7	Input	Interrupt request pins.



Note: This figure indicates the power supply pins and I/O port pins.
For the pin configuration, see the table “List of Pins and Pin Functions (64-Pin LFQFP/HWQFN)”.

Note 1. RX230: PH0, PH1, PH2, PH3
RX231: VSS_USB, USB0_DP, USB0_DM, VCC_USB

Figure 1.7 Pin Assignments of the 64-Pin LFQFP

Table 1.8 List of Pins and Pin Functions (64-Pin WFLGA) (1/2)

Pin No.	Power Supply, Clock, System Control	I/O Port	Timers (MTU, TPU, TMR, RTC, CMT, POE, CAC)	Communications (SCI, RSPI, RIIC, RSCAN, USB, SSI)	Memory Interface (SDHI)	Touch sensing	Others
A1		P05					DA1
A2	AVCC0						
A3	VREFH0						
A4	VREFL0						
A5	VREFH						
A6	VREFL						
A7		PE2	MTIOC4A	RXD12/RXDX12/SMISO12/ SSCL12			IRQ7/AN018/ CVREFB0
A8		PE3	MTIOC4B/POE8#	CTS12#/RTS12#/SS12#/ AUDIO_MCLK			AN019/CLKOUT
B1	VCL						
B2	AVSS0						
B3		P40					AN000
B4		P42					AN002
B5		P44					AN004
B6		P46					AN006
B7		PE1	MTIOC4C	TXD12/TXDX12/SIOX12/ SMOSI12/SSDA12			AN017/CMPB0
B8		PE4	MTIOC4D/MTIOC1A				AN020/CMPA2/ CLKOUT
C1	XCIN						
C2	MD						FINED
C3		P03					DA0
C4		P41					AN001
C5		P43					AN003
C6		PE0		SCK12			AN016
C7		PE5	MTIOC4C/MTIOC2B				IRQ5/AN021/ CMPOB0
C8		PA0	MTIOC4A/TIOCA0	SSLA1			CACREF
D1	XCOUT						
D2	RES#						
D3		P27	MTIOC2B/TMCI3	SCK1/ SSIWS0		TS2	CVREFB3
D4		P14	MTIOC3A/MTCLKA/TMRI2/ TIOCB5/TCLKA	CTS1#/RTS1#/SS1#/CTXD0/ USB0_OVRCURA		TS13	IRQ4/CVREFB2
D5		PA6	MTIC5V/MTCLKB/TMCI3/POE2#/ TIOCA2	CTS5#/RTS5#/SS5#/MOSIA/ SSIWS0			
D6		PA4	MTIC5U/MTCLKA/TMRI0/TIOCA1	TXD5/SMOSI5/SSDA5/SSLA0/ SSITXD0/IRTXD5			IRQ5 /CVREFB1
D7		PA1	MTIOC0B/MTCLKC/TIOCB0	SCK5/SSLA2/SSISCK0			
D8		PA3	MTIOC0D/MTCLKD/TIOCD0/ TCLKB	RXD5/SMISO5/SSCL5/SSIRXD0/ IRRXD5			IRQ6 /CMPB1
E1	VSS						
E2	VBATT						
E3		P30	MTIOC4B/TMRI3/POE8#/RTCIC0	RXD1/SMISO1/SSCL1/ AUDIO_MCLK			IRQ0/CMPOB3
E4		P16	MTIOC3C/MTIOC3D/TMO2/ TIOCB1/TCLKC/RTCOUT	TXD1/SMOSI1/SSDA1/MOSIA/ SCL/USB0_VBUS/ USB0_VBUSEN/ USB0_OVRCURB			IRQ6/ADTRG0#
E5		PC4	MTIOC3D/MTCLKC/TMCI1/ POE0#	SCK5/CTS8#/RTS8#/SS8#/ SSLA0	SDHI_D1	TSCAP	
E6	VCC						
E7	VSS						
E8		PB0	MTIC5W/TIOCA3	RXD6/SMISO6/SSCL6/RSPCKA	SDHI_C MD		
F1	VCC						
F2	UPSEL	P35					NMI
F3		P31	MTIOC4D/TMCI2/RTCIC1	CTS1#/RTS1#/SS1#/SSISCK0			IRQ1

Table 4.1 List of I/O Registers (Address Order) (9/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 90AAh	S12AD	A/D Compare Function Window B Upper-Side Level Setting Register	ADWINULB	16	16	2 or 3 PCLKB	2 ICLK
0008 90ACh	S12AD	A/D Compare Function Window B Channel Status Register	ADCMPBSR	8	8	2 or 3 PCLKB	2 ICLK
0008 90B0h	S12AD	A/D Data Storage Buffer Register 0	ADBUF0	16	16	2 or 3 PCLKB	2 ICLK
0008 90B2h	S12AD	A/D Data Storage Buffer Register 1	ADBUF1	16	16	2 or 3 PCLKB	2 ICLK
0008 90B4h	S12AD	A/D Data Storage Buffer Register 2	ADBUF2	16	16	2 or 3 PCLKB	2 ICLK
0008 90B6h	S12AD	A/D Data Storage Buffer Register 3	ADBUF3	16	16	2 or 3 PCLKB	2 ICLK
0008 90B8h	S12AD	A/D Data Storage Buffer Register 4	ADBUF4	16	16	2 or 3 PCLKB	2 ICLK
0008 90BAh	S12AD	A/D Data Storage Buffer Register 5	ADBUF5	16	16	2 or 3 PCLKB	2 ICLK
0008 90BCh	S12AD	A/D Data Storage Buffer Register 6	ADBUF6	16	16	2 or 3 PCLKB	2 ICLK
0008 90BEh	S12AD	A/D Data Storage Buffer Register 7	ADBUF7	16	16	2 or 3 PCLKB	2 ICLK
0008 90C0h	S12AD	A/D Data Storage Buffer Register 8	ADBUF8	16	16	2 or 3 PCLKB	2 ICLK
0008 90C2h	S12AD	A/D Data Storage Buffer Register 9	ADBUF9	16	16	2 or 3 PCLKB	2 ICLK
0008 90C4h	S12AD	A/D Data Storage Buffer Register 10	ADBUF10	16	16	2 or 3 PCLKB	2 ICLK
0008 90C6h	S12AD	A/D Data Storage Buffer Register 11	ADBUF11	16	16	2 or 3 PCLKB	2 ICLK
0008 90C8h	S12AD	A/D Data Storage Buffer Register 12	ADBUF12	16	16	2 or 3 PCLKB	2 ICLK
0008 90CAh	S12AD	A/D Data Storage Buffer Register 13	ADBUF13	16	16	2 or 3 PCLKB	2 ICLK
0008 90CCh	S12AD	A/D Data Storage Buffer Register 14	ADBUF14	16	16	2 or 3 PCLKB	2 ICLK
0008 90CEh	S12AD	A/D Data Storage Buffer Register 15	ADBUF15	16	16	2 or 3 PCLKB	2 ICLK
0008 90D0h	S12AD	A/D Data Storage Buffer Enable Register	ADBUFEN	8	8	2 or 3 PCLKB	2 ICLK
0008 90D2h	S12AD	A/D Data Storage Buffer Pointer Register	ADBUFPTR	8	8	2 or 3 PCLKB	2 ICLK
0008 90DDh	S12AD	A/D Sampling State Register L	ADSSTRL	8	8	2 or 3 PCLKB	2 ICLK
0008 90DEh	S12AD	A/D Sampling State Register T	ADSSTRT	8	8	2 or 3 PCLKB	2 ICLK
0008 90DFh	S12AD	A/D Sampling State Register O	ADSSTRO	8	8	2 or 3 PCLKB	2 ICLK
0008 90E0h	S12AD	A/D Sampling State Register 0	ADSSTR0	8	8	2 or 3 PCLKB	2 ICLK
0008 90E1h	S12AD	A/D Sampling State Register 1	ADSSTR1	8	8	2 or 3 PCLKB	2 ICLK
0008 90E2h	S12AD	A/D Sampling State Register 2	ADSSTR2	8	8	2 or 3 PCLKB	2 ICLK
0008 90E3h	S12AD	A/D Sampling State Register 3	ADSSTR3	8	8	2 or 3 PCLKB	2 ICLK
0008 90E4h	S12AD	A/D Sampling State Register 4	ADSSTR4	8	8	2 or 3 PCLKB	2 ICLK
0008 90E5h	S12AD	A/D Sampling State Register 5	ADSSTR5	8	8	2 or 3 PCLKB	2 ICLK
0008 90E6h	S12AD	A/D Sampling State Register 6	ADSSTR6	8	8	2 or 3 PCLKB	2 ICLK
0008 90E7h	S12AD	A/D Sampling State Register 7	ADSSTR7	8	8	2 or 3 PCLKB	2 ICLK
0008 A000h	SCI0	Serial Mode Register	SMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A001h	SCI0	Bit Rate Register	BRR	8	8	2 or 3 PCLKB	2 ICLK
0008 A002h	SCI0	Serial Control Register	SCR	8	8	2 or 3 PCLKB	2 ICLK
0008 A003h	SCI0	Transmit Data Register	TDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A004h	SCI0	Serial Status Register	SSR	8	8	2 or 3 PCLKB	2 ICLK
0008 A005h	SCI0	Receive Data Register	RDR	8	8	2 or 3 PCLKB	2 ICLK
0008 A006h	SCI0	Smart Card Mode Register	SCMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A007h	SCI0	Serial Extended Mode Register	SEMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A008h	SCI0	Noise Filter Setting Register	SNFR	8	8	2 or 3 PCLKB	2 ICLK
0008 A009h	SCI0	I^2C Mode Register 1	SIMR1	8	8	2 or 3 PCLKB	2 ICLK
0008 A00Ah	SCI0	I^2C Mode Register 2	SIMR2	8	8	2 or 3 PCLKB	2 ICLK
0008 A00Bh	SCI0	I^2C Mode Register 3	SIMR3	8	8	2 or 3 PCLKB	2 ICLK
0008 A00Ch	SCI0	I^2C Status Register	SISR	8	8	2 or 3 PCLKB	2 ICLK
0008 A00Dh	SCI0	SPI Mode Register	SPMR	8	8	2 or 3 PCLKB	2 ICLK
0008 A00Eh	SCI0	Transmit Data Register HL	TDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A00Eh	SCI0	Transmit Data Register H	TDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A00Fh	SCI0	Transmit Data Register L	TDRL	8	8	2 or 3 PCLKB	2 ICLK
0008 A010h	SCI0	Receive Data Register HL	RDRHL	16	16	4 or 5 PCLKB	2 ICLK
0008 A010h	SCI0	Receive Data Register H	RDRH	8	8	2 or 3 PCLKB	2 ICLK
0008 A011h	SCI0	Receive Data Register L	RDRL	8	8	2 or 3 PCLKB	2 ICLK

Table 4.1 List of I/O Registers (Address Order) (17/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
0008 C0A4h	PORTJ	Open Drain Control Register 0	ODR0	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C0C0h	PORT0	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C1h	PORT1	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C2h	PORT2	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C3h	PORT3	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C4h	PORT4	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0C5h	PORT5	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CAh	PORTA	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CBh	PORTB	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CCh	PORTC	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CDh	PORTD	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0CEh	PORTE	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0D1h	PORTH	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0D2h	PORTJ	Pull-Up Control Register	PCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E1h	PORT1	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E2h	PORT2	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E3h	PORT3	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0E5h	PORT5	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EAh	PORTA	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EBh	PORTB	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0ECh	PORTC	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EDh	PORTD	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0EEh	PORTE	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0F1h	PORTH	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C0F2h	PORTJ	Drive Capacity Control Register	DSCR	8	8	2 or 3 PCLKB	2 ICLK
0008 C100h	MPC	CS Output Enable Register	PFCSE	8	8	2 or 3 PCLKB	2 ICLK
0008 C104h	MPC	Address Output Enable Register 0	PFAOE0	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C105h	MPC	Address Output Enable Register 1	PFAOE1	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C106h	MPC	External Bus Control Register 0	PFBCR0	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C107h	MPC	External Bus Control Register 1	PFBCR1	8	8, 16	2 or 3 PCLKB	2 ICLK
0008 C11Fh	MPC	Write-Protect Register	PWPR	8	8	2 or 3 PCLKB	2 ICLK
0008 C120h	PORT	Port Switching Register B	PSRB	8	8	2 or 3 PCLKB	2 ICLK
0008 C121h	PORT	Port Switching Register A	PSRA	8	8	2 or 3 PCLKB	2 ICLK
0008 C143h	MPC	P03 Pin Function Control Register	P03PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C145h	MPC	P05 Pin Function Control Register	P05PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C147h	MPC	P07 Pin Function Control Register	P07PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Ah	MPC	P12 Pin Function Control Register	P12PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Bh	MPC	P13 Pin Function Control Register	P13PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Ch	MPC	P14 Pin Function Control Register	P14PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Dh	MPC	P15 Pin Function Control Register	P15PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Eh	MPC	P16 Pin Function Control Register	P16PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C14Fh	MPC	P17 Pin Function Control Register	P17PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C150h	MPC	P20 Pin Function Control Register	P20PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C151h	MPC	P21 Pin Function Control Register	P21PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C152h	MPC	P22 Pin Function Control Register	P22PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C153h	MPC	P23 Pin Function Control Register	P23PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C154h	MPC	P24 Pin Function Control Register	P24PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C155h	MPC	P25 Pin Function Control Register	P25PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C156h	MPC	P26 Pin Function Control Register	P26PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C157h	MPC	P27 Pin Function Control Register	P27PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C158h	MPC	P30 Pin Function Control Register	P30PFS	8	8	2 or 3 PCLKB	2 ICLK
0008 C159h	MPC	P31 Pin Function Control Register	P31PFS	8	8	2 or 3 PCLKB	2 ICLK

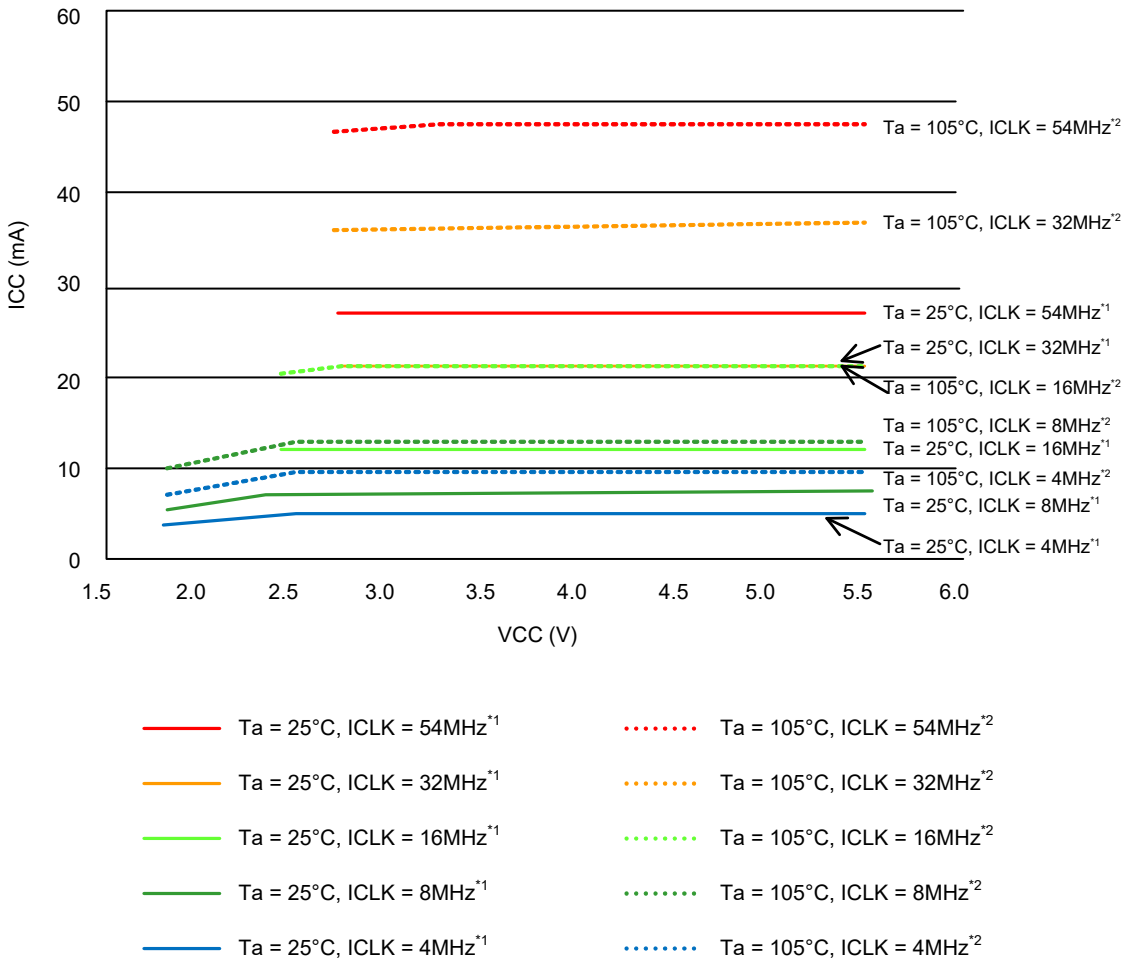
Table 4.1 List of I/O Registers (Address Order) (29/33)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles	
						ICLK ≥ PCLK	ICLK <PCLK
000A 8494h	RSCAN	Receive Buffer Register 15BL	RMTS15	16	16	2 or 3 PCLKB	2 ICLK
000A 8496h	RSCAN	Receive Buffer Register 15BH	RMPTR15	16	16	2 or 3 PCLKB	2 ICLK
000A 8498h	RSCAN	Receive Buffer Register 15CL	RMDF015	16	16	2 or 3 PCLKB	2 ICLK
000A 849Ah	RSCAN	Receive Buffer Register 15CH	RMDF115	16	16	2 or 3 PCLKB	2 ICLK
000A 849Ch	RSCAN	Receive Buffer Register 15DL	RMDF215	16	16	2 or 3 PCLKB	2 ICLK
000A 849Eh	RSCAN	Receive Buffer Register 15DH	RMDF315	16	16	2 or 3 PCLKB	2 ICLK
000A 8580h to 000A 859Fh	RSCAN	RAM Test Register 0 to RAM Test Register 15	RPGACC0 to RPGACC15	16	16	2 or 3 PCLKB	2 ICLK
000A 85A0h	RSCAN	Receive FIFO Access Register 0AL	RFIDL0	16	16	2 or 3 PCLKB	2 ICLK
000A 85A0h	RSCAN	RAM Test Register 16	RPGACC16	16	16	2 or 3 PCLKB	2 ICLK
000A 85A2h	RSCAN	Receive FIFO Access Register 0AH	RFIDH0	16	16	2 or 3 PCLKB	2 ICLK
000A 85A2h	RSCAN	RAM Test Register 17	RPGACC17	16	16	2 or 3 PCLKB	2 ICLK
000A 85A4h	RSCAN	Receive FIFO Access Register 0BL	RFTS0	16	16	2 or 3 PCLKB	2 ICLK
000A 85A4h	RSCAN	RAM Test Register 18	RPGACC18	16	16	2 or 3 PCLKB	2 ICLK
000A 85A6h	RSCAN	Receive FIFO Access Register 0BH	RFPTR0	16	16	2 or 3 PCLKB	2 ICLK
000A 85A6h	RSCAN	RAM Test Register 19	RPGACC19	16	16	2 or 3 PCLKB	2 ICLK
000A 85A8h	RSCAN	Receive FIFO Access Register 0CL	RFDF00	16	16	2 or 3 PCLKB	2 ICLK
000A 85A8h	RSCAN	RAM Test Register 20	RPGACC20	16	16	2 or 3 PCLKB	2 ICLK
000A 85AAh	RSCAN	Receive FIFO Access Register 0CH	RFDF10	16	16	2 or 3 PCLKB	2 ICLK
000A 85AAh	RSCAN	RAM Test Register 21	RPGACC21	16	16	2 or 3 PCLKB	2 ICLK
000A 85ACh	RSCAN	Receive FIFO Access Register 0DL	RFDF20	16	16	2 or 3 PCLKB	2 ICLK
000A 85ACh	RSCAN	RAM Test Register 22	RPGACC22	16	16	2 or 3 PCLKB	2 ICLK
000A 85AEh	RSCAN	Receive FIFO Access Register 0DH	RFDF30	16	16	2 or 3 PCLKB	2 ICLK
000A 85AEh	RSCAN	RAM Test Register 23	RPGACC23	16	16	2 or 3 PCLKB	2 ICLK
000A 85B0h	RSCAN	Receive FIFO Access Register 1AL	RFIDL1	16	16	2 or 3 PCLKB	2 ICLK
000A 85B0h	RSCAN	RAM Test Register 24	RPGACC24	16	16	2 or 3 PCLKB	2 ICLK
000A 85B2h	RSCAN	Receive FIFO Access Register 1AH	RFIDH1	16	16	2 or 3 PCLKB	2 ICLK
000A 85B2h	RSCAN	RAM Test Register 25	RPGACC25	16	16	2 or 3 PCLKB	2 ICLK
000A 85B4h	RSCAN	Receive FIFO Access Register 1BL	RFTS1	16	16	2 or 3 PCLKB	2 ICLK
000A 85B4h	RSCAN	RAM Test Register 26	RPGACC26	16	16	2 or 3 PCLKB	2 ICLK
000A 85B6h	RSCAN	Receive FIFO Access Register 1BH	RFPTR1	16	16	2 or 3 PCLKB	2 ICLK
000A 85B6h	RSCAN	RAM Test Register 27	RPGACC27	16	16	2 or 3 PCLKB	2 ICLK
000A 85B8h	RSCAN	Receive FIFO Access Register 1CL	RFDF01	16	16	2 or 3 PCLKB	2 ICLK
000A 85B8h	RSCAN	RAM Test Register 28	RPGACC28	16	16	2 or 3 PCLKB	2 ICLK
000A 85BAh	RSCAN	Receive FIFO Access Register 1CH	RFDF11	16	16	2 or 3 PCLKB	2 ICLK
000A 85BAh	RSCAN	RAM Test Register 29	RPGACC29	16	16	2 or 3 PCLKB	2 ICLK
000A 85BCh	RSCAN	Receive FIFO Access Register 1DL	RFDF21	16	16	2 or 3 PCLKB	2 ICLK
000A 85BCh	RSCAN	RAM Test Register 30	RPGACC30	16	16	2 or 3 PCLKB	2 ICLK
000A 85BEh	RSCAN	Receive FIFO Access Register 1DH	RFDF31	16	16	2 or 3 PCLKB	2 ICLK
000A 85BEh	RSCAN	RAM Test Register 31	RPGACC31	16	16	2 or 3 PCLKB	2 ICLK
000A 85C0h to 000A 85DEh	RSCAN	RAM Test Register 32 to RAM Test Register 47	RPGACC32 to RPGACC47	16	16	2 or 3 PCLKB	2 ICLK
000A 85E0h	RSCAN0	Transmit/Receive FIFO Access Register 0AL	CFIDL0	16	16	2 or 3 PCLKB	2 ICLK
000A 85E0h	RSCAN	RAM Test Register 48	RPGACC48	16	16	2 or 3 PCLKB	2 ICLK
000A 85E2h	RSCAN0	Transmit/Receive FIFO Access Register 0AH	CFIDH0	16	16	2 or 3 PCLKB	2 ICLK
000A 85E2h	RSCAN	RAM Test Register 49	RPGACC49	16	16	2 or 3 PCLKB	2 ICLK
000A 85E4h	RSCAN0	Transmit/Receive FIFO Access Register 0BL	CFTS0	16	16	2 or 3 PCLKB	2 ICLK
000A 85E4h	RSCAN	RAM Test Register 50	RPGACC50	16	16	2 or 3 PCLKB	2 ICLK
000A 85E6h	RSCAN0	Transmit/Receive FIFO Access Register 0BH	CFPTR0	16	16	2 or 3 PCLKB	2 ICLK
000A 85E6h	RSCAN	RAM Test Register 51	RPGACC51	16	16	2 or 3 PCLKB	2 ICLK
000A 85E8h	RSCAN0	Transmit/Receive FIFO Access Register 0CL	CFDF00	16	16	2 or 3 PCLKB	2 ICLK
000A 85E8h	RSCAN	RAM Test Register 52	RPGACC52	16	16	2 or 3 PCLKB	2 ICLK

Table 5.2 Recommended Operating Voltage Conditions

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
Power supply voltages	VCC*1, *2	When USB is not used	1.8	—	5.5	V
		When USB is used When USB regulator is not used	3.0	—	3.6	
		When USB is used When USB regulator is used	4.0	—	5.5	
	VSS		—	0	—	
USB power supply voltages	VCC_USB	When USB regulator is not used	—	VCC	—	V
	VSS_USB		—	0	—	
VBATT power supply voltage	VBATT		1.8	—	5.5	V
Analog power supply voltages	AVCC0*1, *2		1.8	—	5.5	V
	AVSS0		—	0	—	
	VREFH0		1.8	—	AVCC0	
	VREFL0		—	0	—	
	VREFH		1.8	—	AVCC0	
	VREFL		—	0	—	

Note 1. Use AVCC0 and VCC under the following conditions:
AVCC0 and VCC can be set individually within the operating range when VCC ≥ 2.0 V
AVCC0 = VCC when VCC < 2.0 V
Note 2. When powering on the VCC and AVCC0 pins, power them on at the same time or the VCC pin first and then the AVCC0 pin.



Note 1. All peripheral operations except any BGO operation are operating normally. Indicates the average of the typical samples through actual measurement during product evaluation.
Note 2. All peripheral operations except any BGO operation are operating at maximum. Indicates the average of the upper-limit samples through actual measurement during product evaluation.

Figure 5.1 Voltage Dependency in High-Speed Operating Mode (Reference Data)

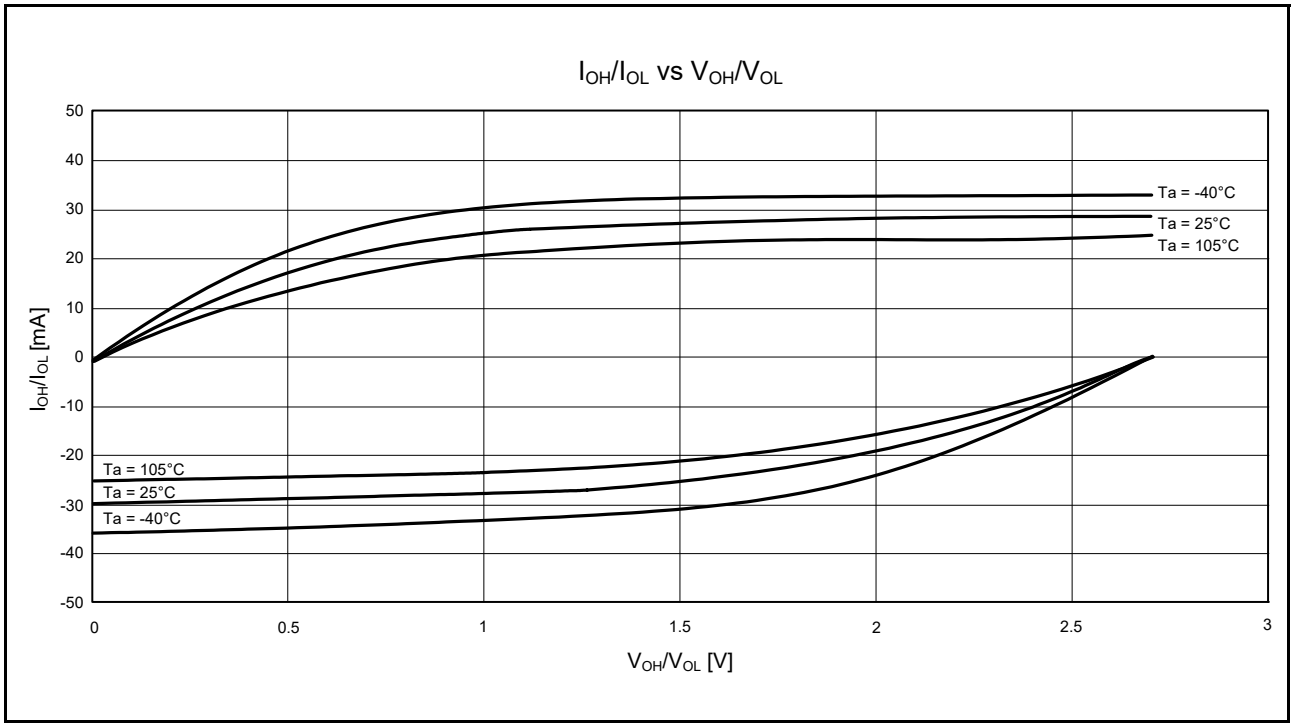


Figure 5.15 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at VCC = 2.7 V When High-Drive Output is Selected (Reference Data)

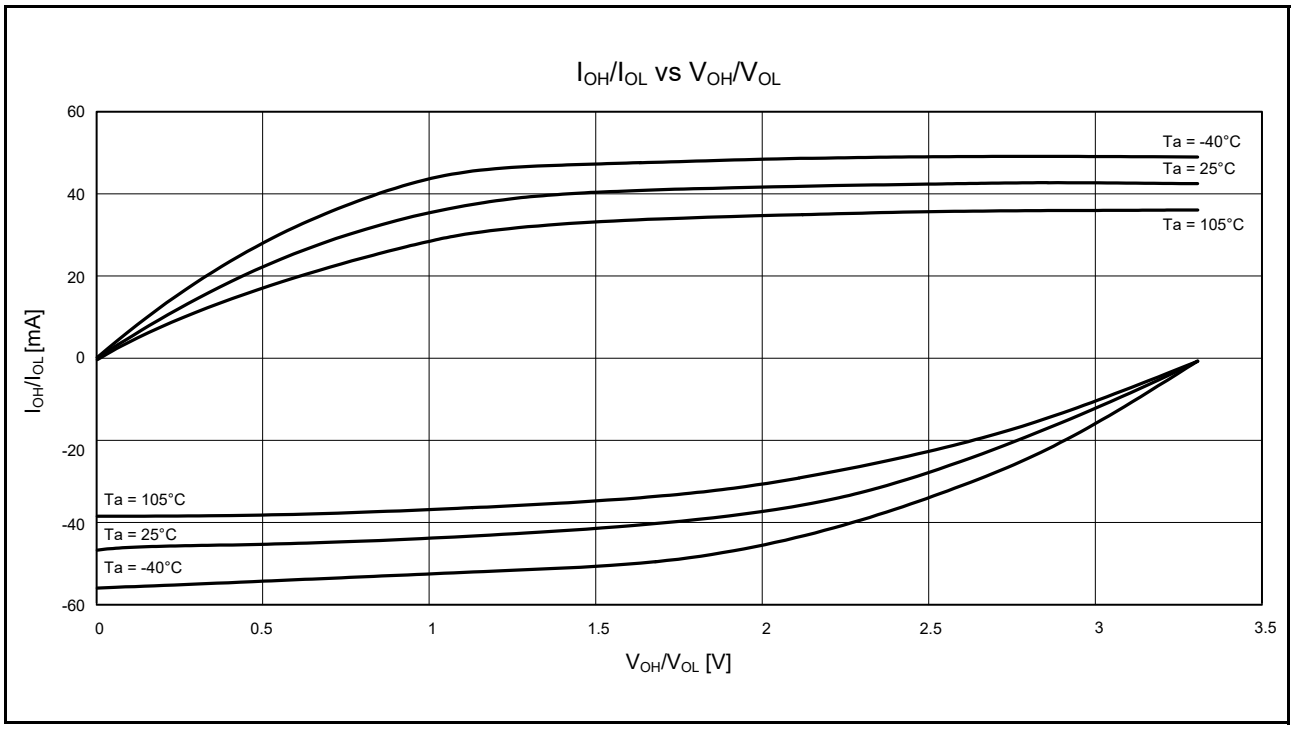


Figure 5.16 V_{OH}/V_{OL} and I_{OH}/I_{OL} Temperature Characteristics at VCC = 3.3 V When High-Drive Output is Selected (Reference Data)

5.3 AC Characteristics

5.3.1 Clock Timing

Table 5.21 Operating Frequency Value (High-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC				Unit
			1.8 V ≤ VCC < 2.4 V	2.4 V ≤ VCC < 2.7 V	2.7 V ≤ VCC ≤ 5.5 V	When USB is in Use*3	
Maximum operating frequency*4	System clock (ICLK)	f_{max}	8	16	54	54	MHz
	FlashIF clock (FCLK)*1, *2		8	16	32	32	
	Peripheral module clock (PCLKA)		8	16	54	54	
	Peripheral module clock (PCLKB)		8	16	32	32	
	Peripheral module clock (PCLKD)		8	32	54	54	
	External bus clock (BCLK)		8	16	32	32	
	BCLK pin output		8	8	16	16	
	USB clock (UCLK)	f_{usb}	—	—	—	48	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When FCLK is in use at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK must be within ±3.5%.
Note 3. The VCC_USB range is 3.0 to 5.5 V when the USB clock is in use.
Note 4. The maximum operating frequency listed above does not include errors of the external oscillator and internal oscillator. For details on the range for the guaranteed operation, see Table 5.26, Clock Timing.

Table 5.22 Operating Frequency Value (Middle-Speed Operating Mode)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	VCC				Unit
			1.8 V ≤ VCC < 2.4 V	2.4 V ≤ VCC < 2.7 V	2.7 V ≤ VCC ≤ 5.5 V	When USB is in Use*3	
Maximum operating frequency*4	System clock (ICLK)	f_{max}	8	12	12	12	MHz
	FlashIF clock (FCLK)*1, *2		8	12	12	12	
	Peripheral module clock (PCLKA)		8	12	12	12	
	Peripheral module clock (PCLKB)		8	12	12	12	
	Peripheral module clock (PCLKD)		8	12	12	12	
	External bus clock (BCLK)		8	12	12	12	
	BCLK pin output		8	8	12	12	
	USB clock (UCLK)	f_{usb}	—	—	—	48	

Note 1. The lower-limit frequency of FCLK is 1 MHz during programming or erasing of the flash memory. When using FCLK at below 4 MHz, the frequency can be set to 1 MHz, 2 MHz, or 3 MHz. A non-integer frequency such as 1.5 MHz cannot be set.
Note 2. The frequency accuracy of FCLK must be within ±3.5%.
Note 3. The VCC_USB range is 3.0 to 5.5 V when the USB clock is in use.
Note 4. The maximum operating frequency listed above does not include errors of the external oscillator and internal oscillator. For details on the range for the guaranteed operation, see Table 5.26, Clock Timing.

Table 5.30 Timing of Recovery from Low Power Consumption Modes (3)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from software standby mode*1	Low-speed mode	Sub-clock oscillator operating	t_{SBYSC}	—	600	750	µs	Figure 5.34

Note 1. The sub-clock continues oscillating in software standby mode during low-speed mode.

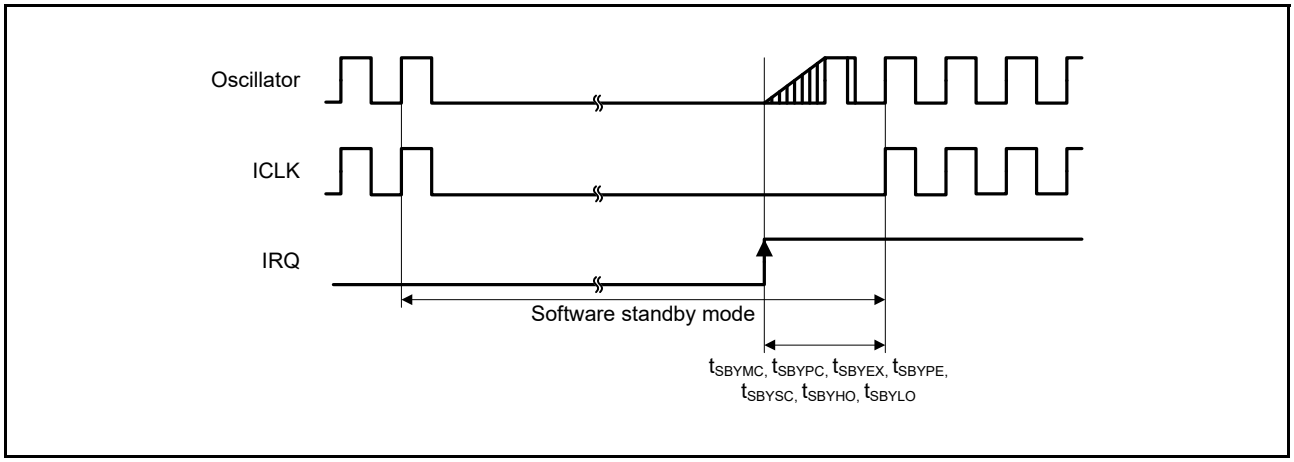


Figure 5.34 Software Standby Mode Recovery Timing

Table 5.31 Timing of Recovery from Low Power Consumption Modes (4)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Recovery time from deep sleep mode*1	High-speed mode*2	t_{DSLP}	—	2	3.5	µs	Figure 5.35
	Middle-speed mode*3	t_{DSLP}	—	3	4	µs	
	Low-speed mode*4	t_{DSLP}	—	400	500	µs	

Note 1. Oscillators continue oscillating in deep sleep mode.
Note 2. When the frequency of the system clock is 32 MHz.
Note 3. When the frequency of the system clock is 12 MHz.
Note 4. When the frequency of the system clock is 32 kHz.

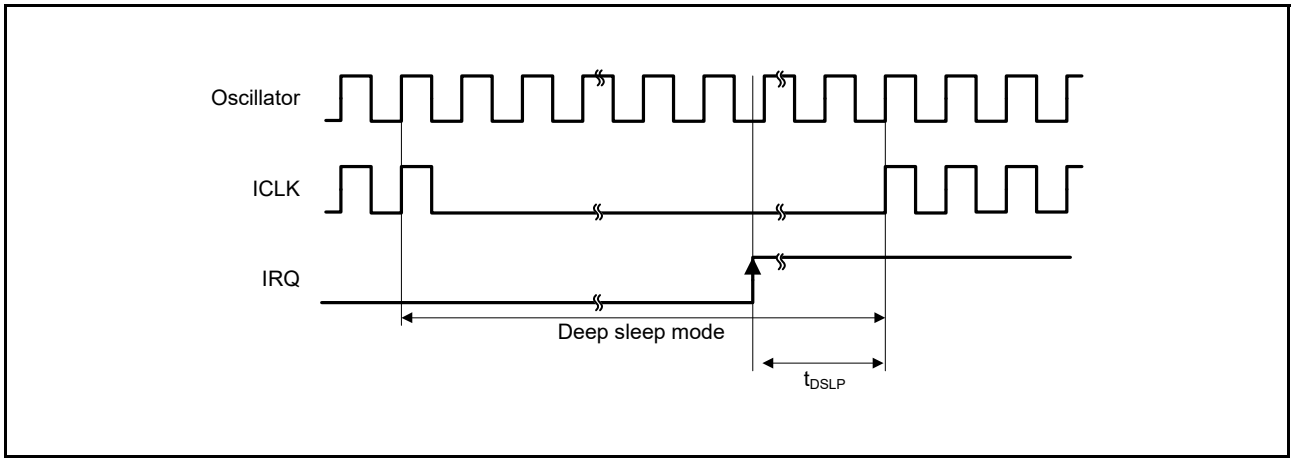


Figure 5.35 Deep Sleep Mode Recovery Timing

Table 5.32 Operating Mode Transition Time

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VREFL0 = VSS_USB = 0 V, T_a = –40 to +105°C

Mode before Transition	Mode after Transition	ICLK Frequency	Transition Time			Unit
			Min.	Typ.	Max.	
High-speed operating mode	Middle-speed operating modes	8 MHz	—	10	—	µs
Middle-speed operating modes	High-speed operating mode	8 MHz	—	37.5	—	µs
Low-speed operating mode	Middle-speed operating mode, high-speed operating mode	32.768 kHz	—	215	—	µs
Middle-speed operating mode, high-speed operating mode	Low-speed operating mode	32.768 kHz	—	185	—	µs

Note: Values when the frequencies of PCLKA, PCLKB, PCLKD, FCLK, and BCLK are not divided.

5.3.4 Control Signal Timing

Table 5.33 Control Signal Timing

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions	
NMI pulse width	t_{NMIW}	200	—	—	ns	NMI digital filter is disabled (NMIFLTE.NFLTEN = 0)	t_{Pcyc} × 2 ≤ 200 ns
		t_{Pcyc} × 2*1	—	—			t_{Pcyc} × 2 > 200 ns
		200	—	—		NMI digital filter is enabled (NMIFLTE.NFLTEN = 1)	t_{NMICK} × 3 ≤ 200 ns
		t_{NMICK} × 3.5*2	—	—			t_{NMICK} × 3 > 200 ns
IRQ pulse width	t_{IRQW}	200	—	—	ns	IRQ digital filter is disabled (IRQFLTE0.FLTENi = 0)	t_{Pcyc} × 2 ≤ 200 ns
		t_{Pcyc} × 2*1	—	—			t_{Pcyc} × 2 > 200 ns
		200	—	—		IRQ digital filter is enabled (IRQFLTE0.FLTENi = 1)	t_{IRQCK} × 3 ≤ 200 ns
		t_{IRQCK} × 3.5*3	—	—			t_{IRQCK} × 3 > 200 ns

Note: 200 ns minimum in software standby mode.
Note 1. t_{Pcyc} indicates the cycle of PCLKB.
Note 2. t_{NMICK} indicates the cycle of the NMI digital filter sampling clock.
Note 3. t_{IRQCK} indicates the cycle of the IRQi digital filter sampling clock (i = 0 to 7).

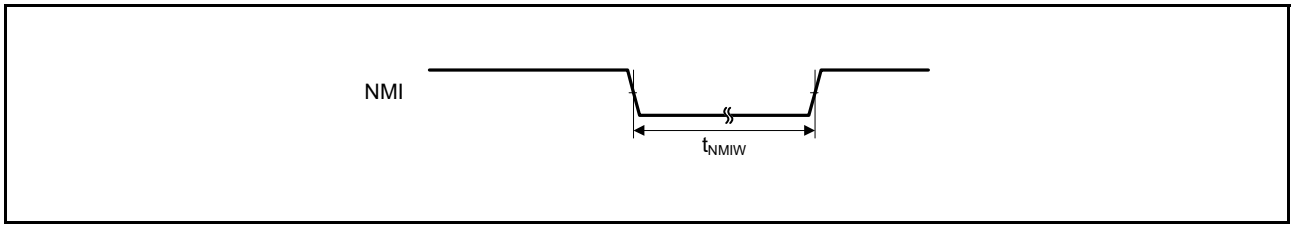


Figure 5.36 NMI Interrupt Input Timing

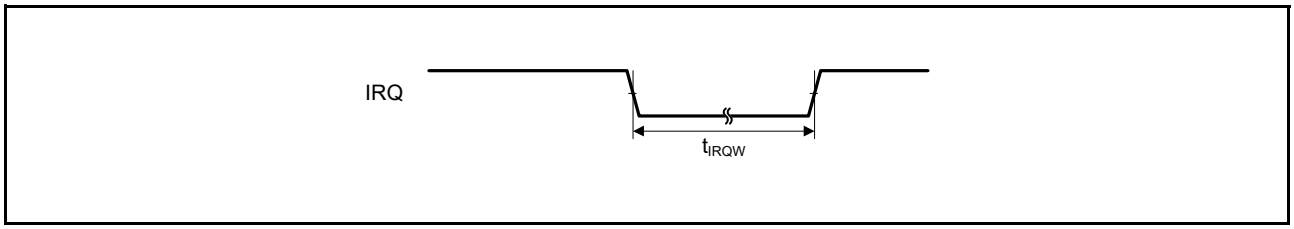
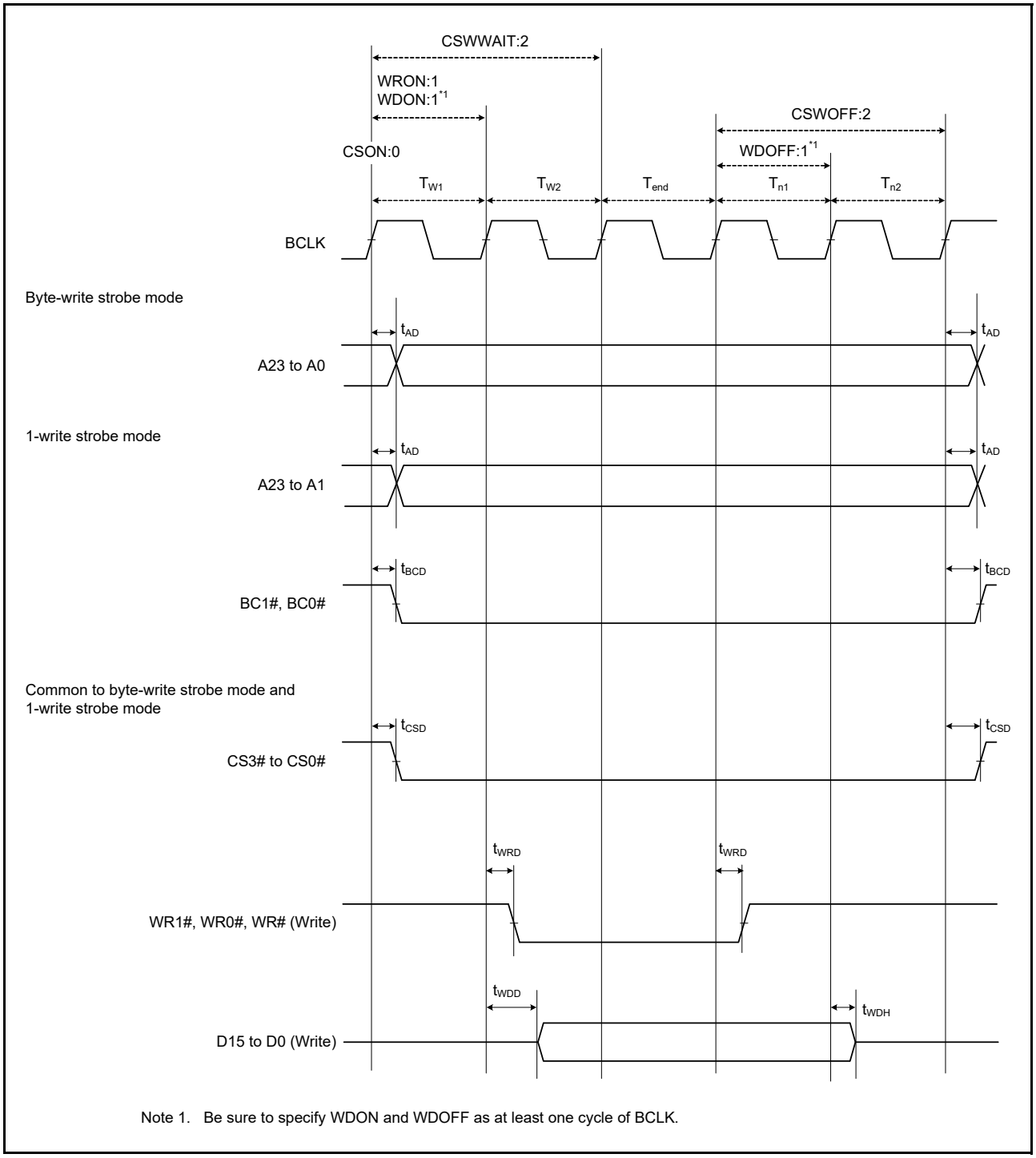


Figure 5.37 IRQ Interrupt Input Timing



Note 1. Be sure to specify WDON and WDOFF as at least one cycle of BCLK.

Figure 5.39 External Bus Timing/Normal Write Cycle (Bus Clock Synchronization)

5.3.6 Timing of On-Chip Peripheral Modules

Table 5.38 Timing of On-Chip Peripheral Modules (1)

Conditions: 1.8 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item			Symbol	Min.	Max.	Unit *1	Test Conditions
I/O ports	Input data pulse width		t_{PRW}	1.5	—	t_{Pcyc}	Figure 5.45
MTU2/TPU	Input capture input pulse width	Single-edge setting	t_{TICW}	1.5	—	t_{Pcyc}	Figure 5.46
		Both-edge setting		2.5	—		
	Timer clock pulse width	Single-edge setting	t_{TCKWH}, t_{TCKWL}	1.5	—	t_{Pcyc}	Figure 5.47
		Both-edge setting		2.5	—		
		Phase counting mode		2.5	—		
POE2	POE# input pulse width		t_{POEW}	1.5	—	t_{Pcyc}	Figure 5.48
TMR	Timer clock pulse width	Single-edge setting	t_{TMCWH}, t_{TMCWL}	1.5	—	t_{Pcyc}	Figure 5.49
		Both-edge setting		2.5	—		
SCI	Input clock cycle time	Asynchronous	t_{Scyc}	4	—	t_{Pcyc}	Figure 5.50
		Clock synchronous		6	—		
	Input clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Input clock rise time		t_{SCKr}	—	20	ns	
	Input clock fall time		t_{SCKf}	—	20	ns	
	Output clock cycle time	Asynchronous	t_{Scyc}	16	—	t_{Pcyc}	Figure 5.51
		Clock synchronous		4	—		
	Output clock pulse width		t_{SCKW}	0.4	0.6	t_{Scyc}	
	Output clock rise time		t_{SCKr}	—	20	ns	
	Output clock fall time		t_{SCKf}	—	20	ns	
	Transmit data delay time (master)	Clock synchronous	t_{TXD}	—	40	ns	
	Transmit data delay time (slave)	Clock synchronous, 2.7 V or above		—	65	ns	
		Clock synchronous, 1.8 V or above		—	100	ns	
	Receive data setup time (master)	Clock synchronous, 2.7 V or above	t_{RXS}	65	—	ns	
		Clock synchronous, 1.8 V or above		90	—	ns	
	Receive data setup time (slave)	Clock synchronous		40	—	ns	
	Receive data hold time	Clock synchronous	t_{RXH}	40	—	ns	
A/D converter	Trigger input pulse width		t_{TRGW}	1.5	—	t_{Pcyc}	Figure 5.52
CAC	CACREF input pulse width	$t_{Pcyc} \le t_{cac}$ *2	t_{CACREF}	4.5 t_{cac} + 3 t_{Pcyc}	—	ns	
		$t_{Pcyc} > t_{cac}$ *2		5 t_{cac} + 6.5 t_{Pcyc}			
CLKOUT	CLKOUT pin output cycle*4	VCC = 2.7 V or above	t_{Ccyc}	62.5	—	ns	Figure 5.53
		VCC = 1.8 V or above		125			
	CLKOUT pin high pulse width*3	VCC = 2.7 V or above	t_{CH}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin low pulse width*3	VCC = 2.7 V or above	t_{CL}	15	—	ns	
		VCC = 1.8 V or above		30			
	CLKOUT pin output rise time	VCC = 2.7 V or above	t_{Cr}	—	12	ns	
		VCC = 1.8 V or above			25		
	CLKOUT pin output fall time	VCC = 2.7 V or above	t_{Cf}	—	12	ns	
		VCC = 1.8 V or above			25		

Note 1. t_{Pcyc}: PCLK cycle
Note 2. t_{cac}: CAC count clock source cycle
Note 3. When the LOCO is selected as the clock output source (the CKOCR.CKOSEL[2:0] bits are 000b), set the clock output division ratio selection to divided by 2 (the CKOCR.CKODIV[2:0] bits are 001b).
Note 4. When the EXTAL external clock input or an oscillator is used with divided by 1 (the CKOCR.CKOSEL[2:0] bits are 010b and the CKOCR.CKODIV[2:0] bits are 000b) to output from CLKOUT, the above should be satisfied with an input duty cycle of 45 to 55%.

Table 5.41 Timing of On-Chip Peripheral Modules (4)

Conditions: 2.7 V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, fPCLKB ≤ 32 MHz, T_a = –40 to +105°C

Item		Symbol	Min.*1, *2	Max.	Unit	Test Conditions
RIIC (Standard mode, SMBus)	SCL cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 1300	—	ns	Figure 5.59
	SCL high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL, SDA rise time	t_{Sr}	—	1000	ns	
	SCL, SDA fall time	t_{Sf}	—	300	ns	
	SCL, SDA spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition setup time	t_{STAS}	1000	—	ns	
	STOP condition setup time	t_{STOS}	1000	—	ns	
	Data setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	
RIIC (Fast mode)	SCL cycle time	t_{SCL}	6 (12) × t_{IICcyc} + 600	—	ns	Figure 5.59
	SCL high pulse width	t_{SCLH}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL low pulse width	t_{SCLL}	3 (6) × t_{IICcyc} + 300	—	ns	
	SCL, SDA rise time	t_{Sr}	—	300	ns	
	SCL, SDA fall time	t_{Sf}	—	300	ns	
	SCL, SDA spike pulse removal time	t_{SP}	0	1 (4) × t_{IICcyc}	ns	
	SDA bus free time	t_{BUF}	3 (6) × t_{IICcyc} + 300	—	ns	
	START condition hold time	t_{STAH}	t_{IICcyc} + 300	—	ns	
	Repeated START condition setup time	t_{STAS}	300	—	ns	
	STOP condition setup time	t_{STOS}	300	—	ns	
	Data setup time	t_{SDAS}	t_{IICcyc} + 50	—	ns	
	Data hold time	t_{SDAH}	0	—	ns	
	SCL, SDA capacitive load	C_b	—	400	pF	

Note: t_{IICcyc}: RIIC internal reference clock (IICφ) cycle

Note 1. The value in parentheses is used when the ICMR3.NF[1:0] bits are set to 11b while a digital filter is enabled with the ICFER.NFE bit = 1.

Note 2. C_b is the total capacitance of the bus lines.

Table 5.49 A/D Conversion Characteristics (4)

Conditions: 2.4V ≤ VCC = VCC_USB = AVCC0 ≤ 5.5V, 2.4V ≤ VREFH0 ≤ AVCC0, VSS = AVSS0 = VSS_USB = 0V, reference voltage = VREFH0 selected, Ta = –40 to +105°C

Item		Min.	Typ.	Max.	Unit	Test Conditions
Frequency		1	—	16	MHz	
Resolution		—	—	12	Bit	
Conversion time*1 (Operation at PCLKD = 16 MHz)	Permissible signal source impedance (Max.) = 2.2 kΩ	3.38	—	—	µs	High-precision channel The ADCSR.ADHSC bit is 1 The ADSSTRn register is 0Dh
		5.06	—	—		Normal-precision channel The ADCSR.ADHSC bit is 1 The ADSSTRn register is 28h
Analog input capacitance	Cs	—	—	15	pF	Pin capacitance included Figure 5.68
Analog input resistance	Rs	—	—	2.5	kΩ	Figure 5.68
Offset error		—	±0.5	±4.5	LSB	
Full-scale error		—	±0.75	±4.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±1.25	±5.0	LSB	High-precision channel
				±8.0	LSB	Other than above
DNL differential non-linearity error		—	±1.0	—	LSB	
INL integral non-linearity error		—	±1.0	±3.0	LSB	

Note: The characteristics apply when no pin functions other than A/D converter input are used. Absolute accuracy includes quantization errors. Offset error, full-scale error, DNL differential non-linearity error, and INL integral non-linearity error do not include quantization errors.

Note 1. The conversion time is the sum of the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Table 5.59 Characteristics of Power-On Reset Circuit and Voltage Detection Circuit (2)

Conditions: 1.8 V ≤ VCC0 = VCC_USB = AVCC0 ≤ 5.5 V, VSS = AVSS0 = VSS_USB = 0 V, T_a = –40 to +105°C

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Wait time after power-on reset cancellation	At normal startup*1	t_{POR}	—	9.1	—	ms	Figure 5.74
	During fast startup time*2	t_{POR}	—	1.6	—		
Wait time after voltage monitoring 0 reset cancellation	Power-on voltage monitoring 0 reset disabled*1	t_{LVD0}	—	568	—	µs	Figure 5.75
	Power-on voltage monitoring 0 reset enabled*2		—	100	—		
Wait time after voltage monitoring 1 reset cancellation		t_{LVD1}	—	100	—	µs	Figure 5.76
Wait time after voltage monitoring 2 reset cancellation		t_{LVD2}	—	100	—	µs	Figure 5.77
Response delay time		t_{det}	—	—	350	µs	Figure 5.73
Minimum VCC down time*3		t_{VOFF}	350	—	—	µs	Figure 5.73, VCC = 1.0 V or above
Power-on reset enable time		$t_{W(POR)}$	1	—	—	ms	Figure 5.74, VCC = below 1.0 V
LVD operation stabilization time (after LVD is enabled)		$Td_{(E-A)}$	—	—	300	µs	Figure 5.76, Figure 5.77
Hysteresis width (power-on rest (POR))		V_{PORH}	—	110	—	mV	
Hysteresis width (voltage detection circuit: LVD1 and LVD2)		V_{LVH}	—	70	—	mV	When Vdet1_0 to Vdet1_4 is selected
			—	60	—		When Vdet1_5 to Vdet1_9 is selected
			—	50	—		When Vdet1_A or Vdet1_B is selected
			—	40	—		When Vdet1_C or Vdet1_D is selected
			—	60	—		When LVD2 is selected

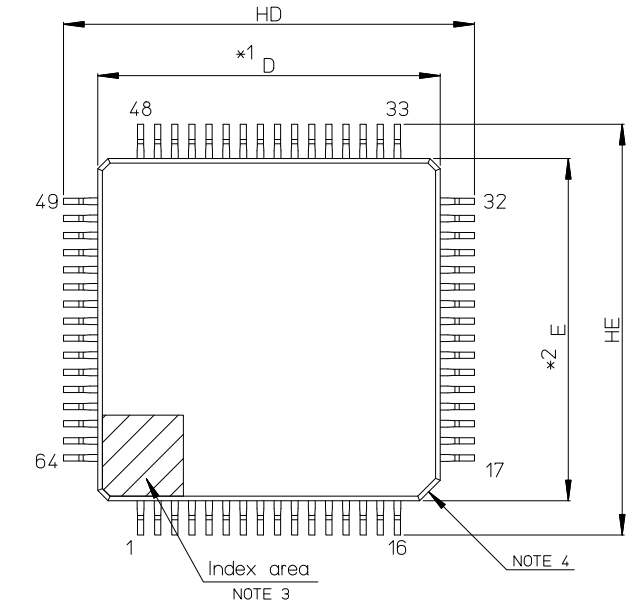
Note: These characteristics apply when noise is not superimposed on the power supply. When a setting is made so that the voltage detection level overlaps with that of the voltage detection circuit (LVD1), it cannot be specified which of LVD1 and LVD2 is used for voltage detection.

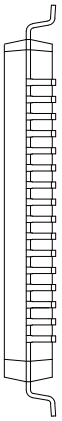
Note 1. When OFS1.(LVDAS, FASTSTUP) = 11b.

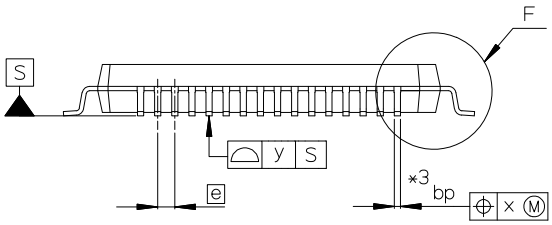
Note 2. When OFS1.(LVDAS, FASTSTUP) ≠ 11b.

Note 3. The minimum VCC down time indicates the time when VCC is below the minimum value of voltage detection levels V_{POR}, V_{det0}, V_{det1}, and V_{det2} for the POR/LVD.

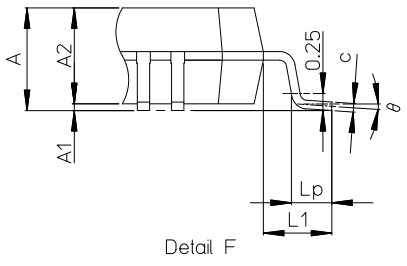
JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LFQFP64-10x10-0.50	PLQP0064KB-C	——	0.3g







NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.
3. PIN 1 VISUAL INDEX FEATURE MAY VARY, BUT MUST BE LOCATED WITHIN THE HATCHED AREA.
4. CHAMFERS AT CORNERS ARE OPTIONAL; SIZE MAY VARY.



Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	9.9	10.0	10.1
E	9.9	10.0	10.1
A2	——	1.4	——
HD	11.8	12.0	12.2
HE	11.8	12.0	12.2
A	——	——	1.7
A1	0.05	——	0.15
bp	0.15	0.20	0.27
c	0.09	——	0.20
θ	0°	3.5°	8°
e	——	0.5	——
x	——	——	0.08
y	——	——	0.08
Lp	0.45	0.6	0.75
L1	——	1.0	——

Figure E 64 -Pin LFQFP (PLQP0064KB-C)